ULTRA LOW-Power Ultra Low-Power Wireless PIR Motion Detector for Cost-Optimized Systems

Revision History

<table>
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<tr>
<th>Rev</th>
<th>ECN #</th>
<th>Approved Date</th>
<th>Approved by</th>
<th>Notes</th>
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</thead>
<tbody>
<tr>
<td>E1</td>
<td>N/A</td>
<td>29 Jan 2016</td>
<td>Gustavo Martinez</td>
<td>Initial Release</td>
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</tbody>
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Project Title: Designed for: Not for Public Release

Assembly Variant: 001

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Version control disabled

SVN Rev: TIDA-01398

Number: Rev: E1

TID #:

Orderable: N/A

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TLV8544 (Amplified Bandpass Filter)

TLV8544 (Window Comparator)

CC2650 (ARM + 2.4 GHz)

Coin Cell Battery (CR2032)

PIR

Vbatt

sensor_out

interrupt
Power and PIR Sensor Signal Conditioning

Battery Connector & Reservoir Capacitors

PIR Bypass Capacitors

PIR Sensor Signal Conditioning

Ultra Low-Power Wireless PIR Motion Detector for Cost-Optimized Systems

TIDA-01398

http://www.ti.com
These assemblies are ESD sensitive. ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

After verifying lens of A1 is clean and undistorted, snap cover H9 over sensor A1 during final hardware assembly.
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